

LOW PROFILE SINGLE CONTACT 201-01-154

1. SPECIFICATION DISTRIBUTION

No restrictions for issue

2. SCOPE

This specification contains the application notes for the 9155 low profile contact.

3. RELATED DOCUMENTS

70-9155-001-6XX-00X – Sales Drawing
201-01-153 – Product Specification

Note: The colours used in this specification are for clarity only.

4. 9155 LOW PROFILE CONTACTS



70-9155-001-610-00X
Nominal working height 1.00mm.



70-9155-001-615-00X
Nominal working height 1.5mm.

4.1. WORKING HEIGHT

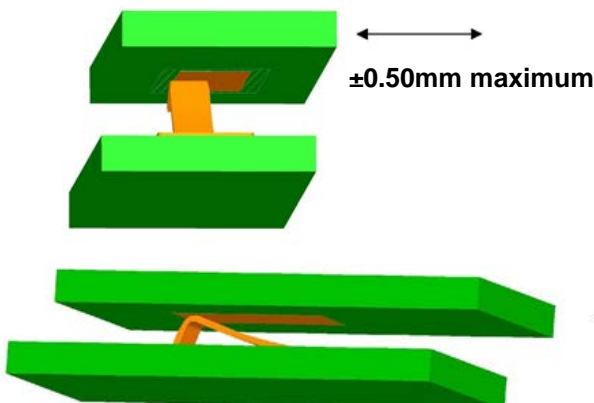


70-9155-001-610-00X with nominal working height 1.00mm can be used with vertical spacing of 0.75mm to 1.25mm. Mated to a pad on a PCB or a device for example a battery.



70-9155-001-615-00X with nominal working height 1.50mm can be used with vertical spacing of 1.25mm to 1.75mm. Mated to a pad on a PCB or a device, for example a battery.

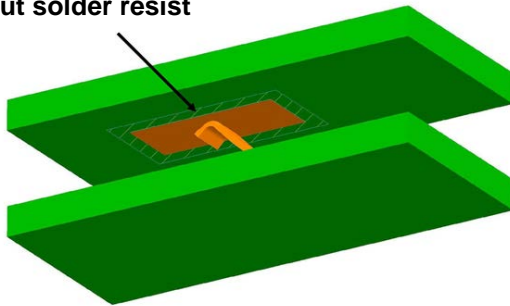
4.2. MAXIMUM PCB MISALIGNMENT



The recommended PCB mating pad layout has been designed to cope with a generous tolerance for misalignment between boards of $\pm 0.50\text{mm}$ side to side and 1.50mm end to end. These tolerances should be regarded as a maximum and in practice we recommend that the misalignment is kept to a minimum.

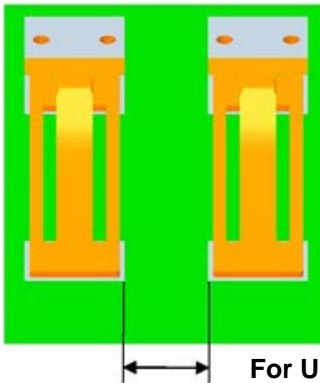
4.3. MATING PAD ON PCB

Area without solder resist



A single pad plated with gold over a nickel under-plate is recommended for good contact under all conditions. Dimensions of pad refer to sales drawing. An area around the mating pad approximately 0.5mm wide should be free of solder resist. This prevents the contact nose riding up on the resist and losing contact with the pad, see also section 4.2 on misalignment above.

4.4. UL REQUIREMENTS FOR PAD SPACING



UL approval based on 3.2mm gap between pads, contact centre spacing 5.9mm.

For non UL applications the gap may be reduced at the customers discretion depending on voltage applied.

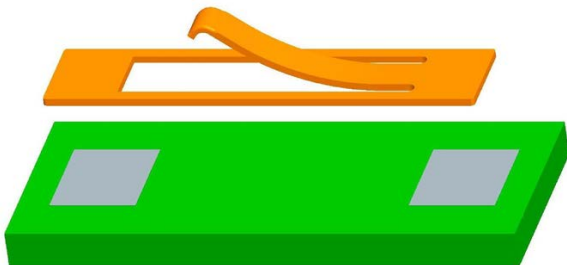
5. CONTACT SMT ASSEMBLY

5.1. PICK AND PLACE

The recommended pick and place area (highlighted here in blue) is 2.70mm wide by 1.75mm long.

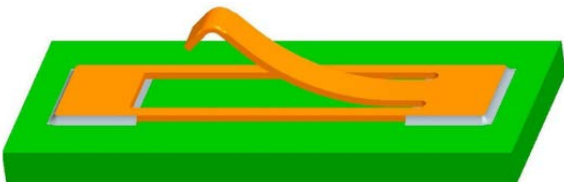


5.2. SMT SOLDER PADS



2 solder pads, refer to sales drawing for dimensions. Placing a pad between these is not recommended as it may affect contact performance. The space between the pads should be kept clear of all tacks and components. It is recommended that solder pads are tin plated.

5.3. SMT SOLDERING



After SMT the contact should be sitting square on the pads and have small fillets all around soldered edges.